

## CH03-BC - SIM CARD HOLDER 6 OR 8 PINS, SLIDE IN TYPE

## FEATURES

## 1. GENERAL CHARACTERISTICS

DIMENSIONS: 25.50L x 17.20W x 2.50H mm

WEIGHT: APPROX. 0.08g

CONTACT PRINCIPLE: FRICTION TECHNOLOGY

OPERATING POSITION: SHAFT UP / DOWN / HORIZONTAL

MOUNTING SYSTEM: SMT TYPE (POST OPTIONAL)

DURABILITY: 10,000 CYCLES MIN.

## 2. MECHANICAL CHARACTERISTICS

INSULATION MATERIAL: THERMOPLASTIC, UL 94V-0

## 3. ELECTRICAL CHARACTERISTICS


NUMBER OF CONTACTS (OPTIONAL): 6, 8 PINS

CONTACT RESISTANCE: 50M OHMS TYP. 100M OHMS MAX.

INSULATION RESISTANCE: &gt; 1000M OHMS / 500V DC

## 4. SOLDERABILITY

WAVE: NOT APPLICABLE

IR REFLOW: 260°C, 10 SEC. MAX. 

MANUAL SOLDERING: 360°C, 3 SEC. MAX.

## 5. ENVIRONMENTAL CHARACTERISTICS

OPERATING TEMPERATURE: -40°C ~ +85°C

OPERATING HUMIDITY: 10% ~ 95% RH

STORAGE TEMPERATURE: -40°C ~ +85°C

STORAGE HUMIDITY: 10% ~ 95% RH

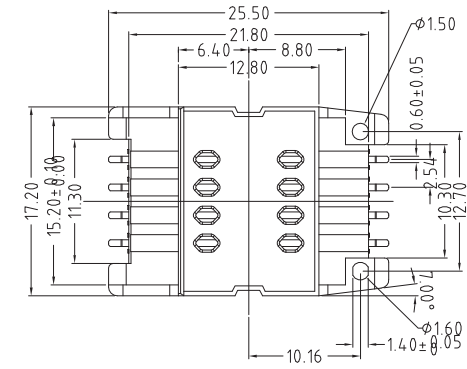
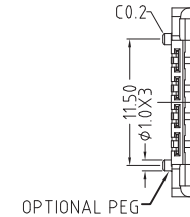
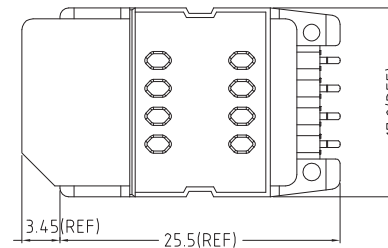
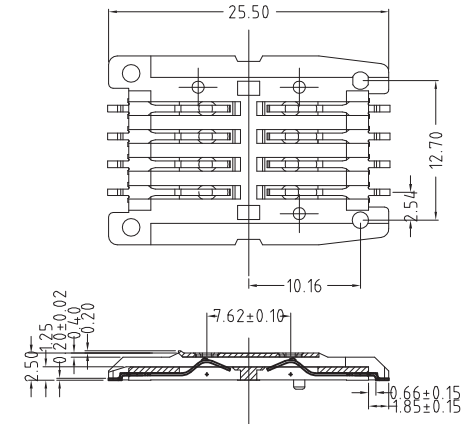
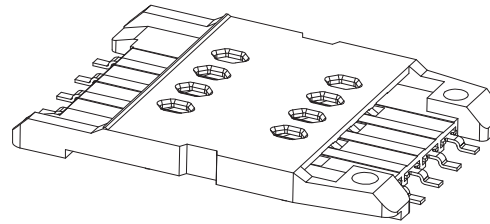
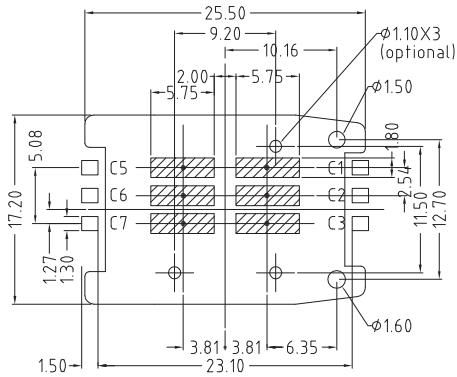
THERMAL SHOCK: -40°C ~ +85°C, 5 CYCLES

DAMP HEAT: 40°C, 90% RH, 500 HR

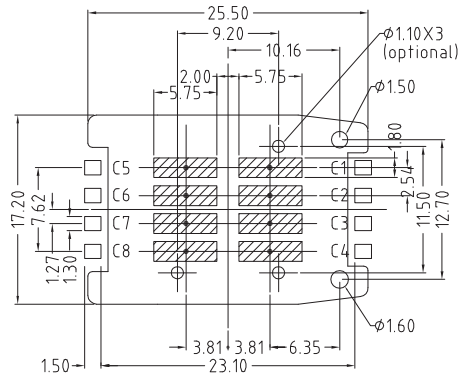
SALT MIST: 35°C, 5%, NaCl, 48 HR

## NOTES:

1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11

SPECIFICATION REQUIREMENT. UNIT:MM  
TOLERANCES:±0.10

6 PINS VERSION



8 PINS VERSION

RECOMMENDED PCB LAYOUT 

## HOW TO ORDER

C H 0 3

- B C X X 0

NO. OF CONTACTS  
06 OR 08

- 0 X R

WITH OR WITHOUT  
LOCATING PEG  
A = WITH  
B = WITHOUT PACKAGING OPTIONS  
R = REEL  
(600PCS/REEL) 

Type: CH03-BC

CH03-BC

Drawing Number:

Sheet 1 of 2

Drawing C  E and O E

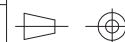
Scale: 2:1

Drawn: NYW

App'd: XXXX

Date: 28 APR '09

THIRD ANGLE



Revision: 1.6


Unstated  
0 Dec Places  
1 Dec Places  
2 Dec Places  
3 Dec Places

Tolerances:

Material  
SEE NOTE

NOT TO SCALE

Unit: mm

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